

A TPC for the Linear Collider

P. Colas

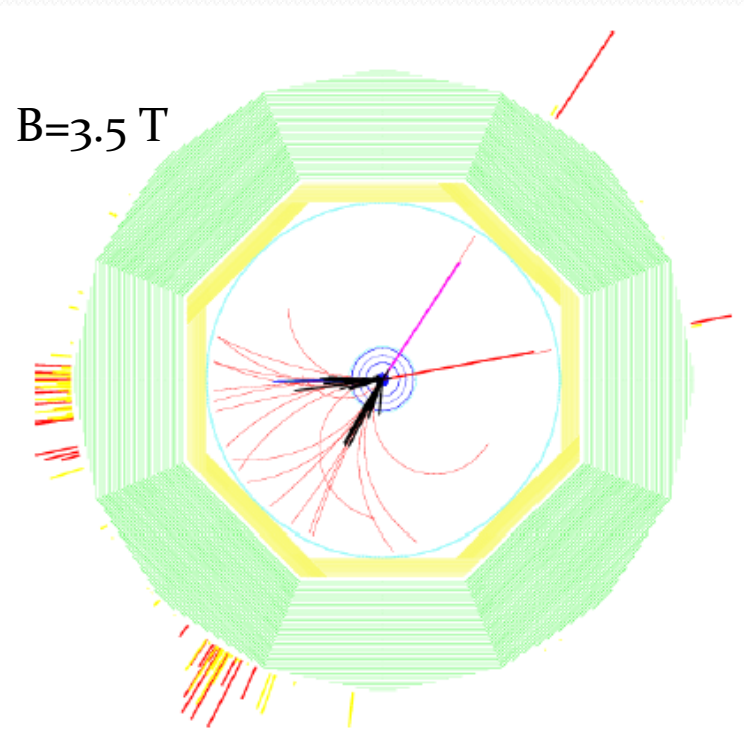
on behalf of LCTPC



2 detector concepts : ILD and SiD

Both based on the 'particle flow' paradigm

- SiD: all-silicon
- ILD: TPC for the central tracking



Benchmark process: $e+e^- \rightarrow HZ, Z \rightarrow \mu\mu$

Requirements:

Momentum resolution

$\delta(1/p_T) < 2.10^{-5} \text{ GeV}/c$ with vertex constraint

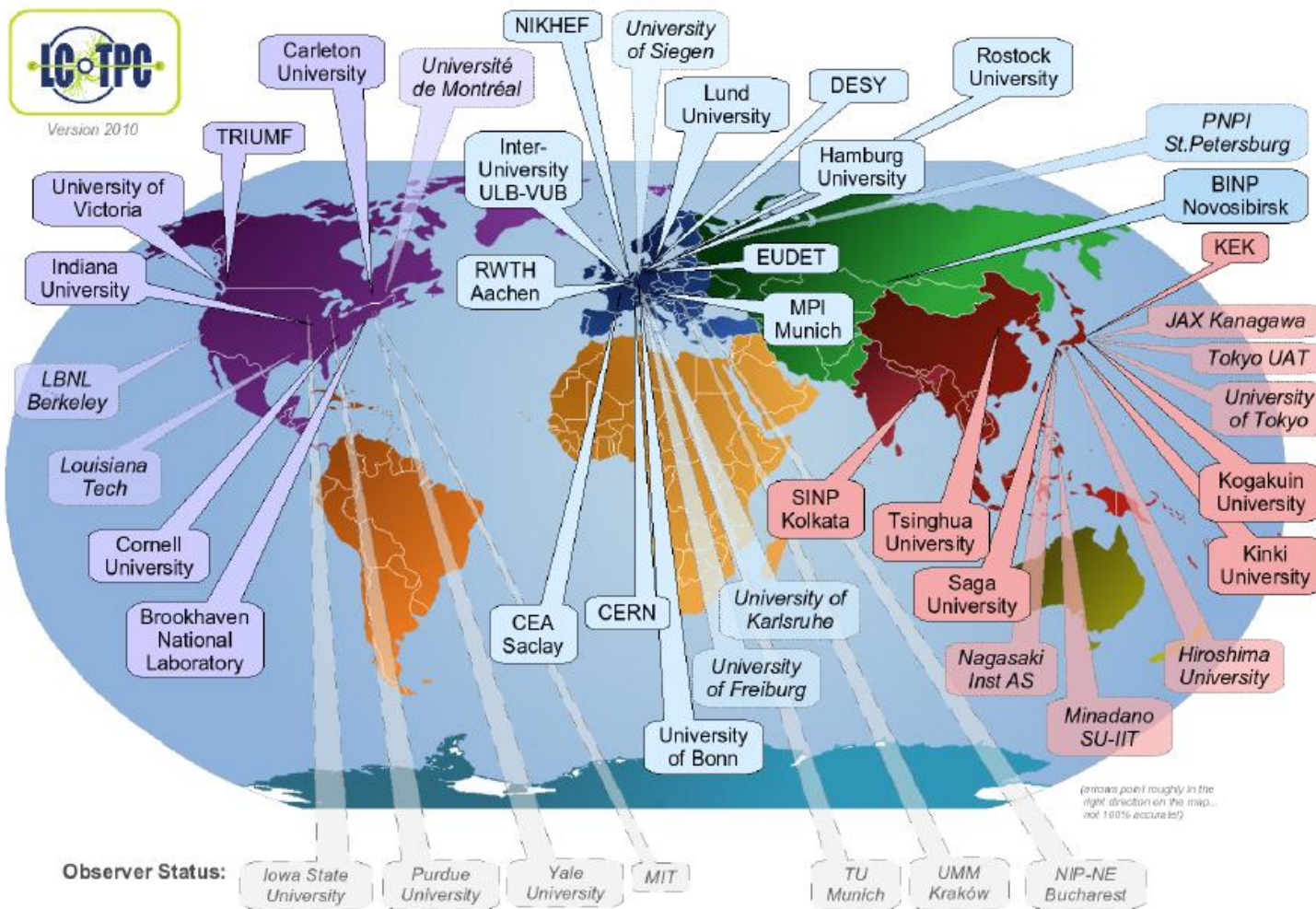
$\delta(1/p_T) < 9.10^{-5} \text{ GeV}/c$ TPC only

(200 points with 100 μ resolution in $R\phi$)

2-track separation: 2 mm in $R\phi$ and 6 mm in z
in a high density background

Material budget: $< 5\% X_0$ in the barrel region,
 $< 25\% X_0$ in the endcap region

All the R&D is gathered in LCTPC



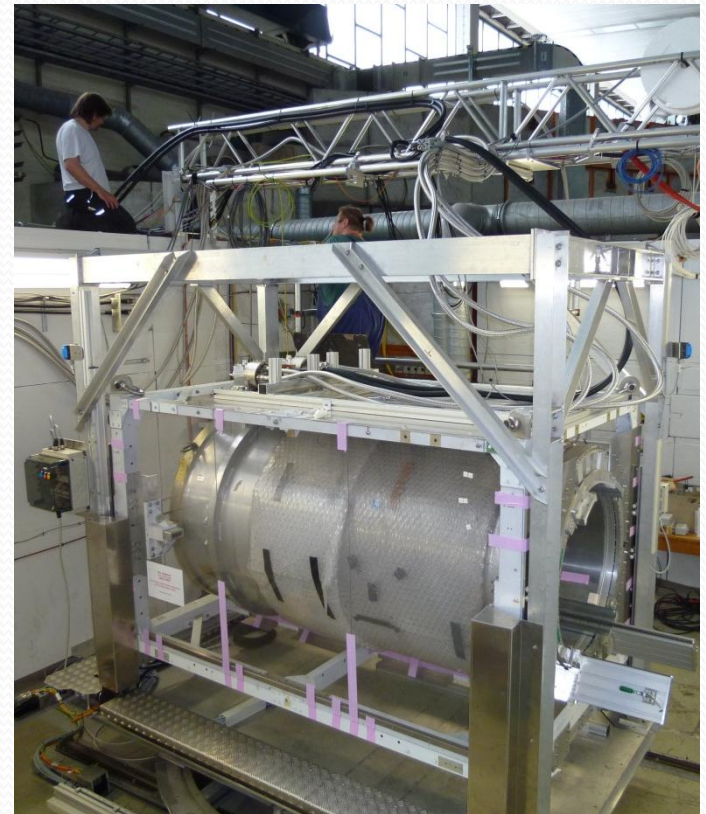
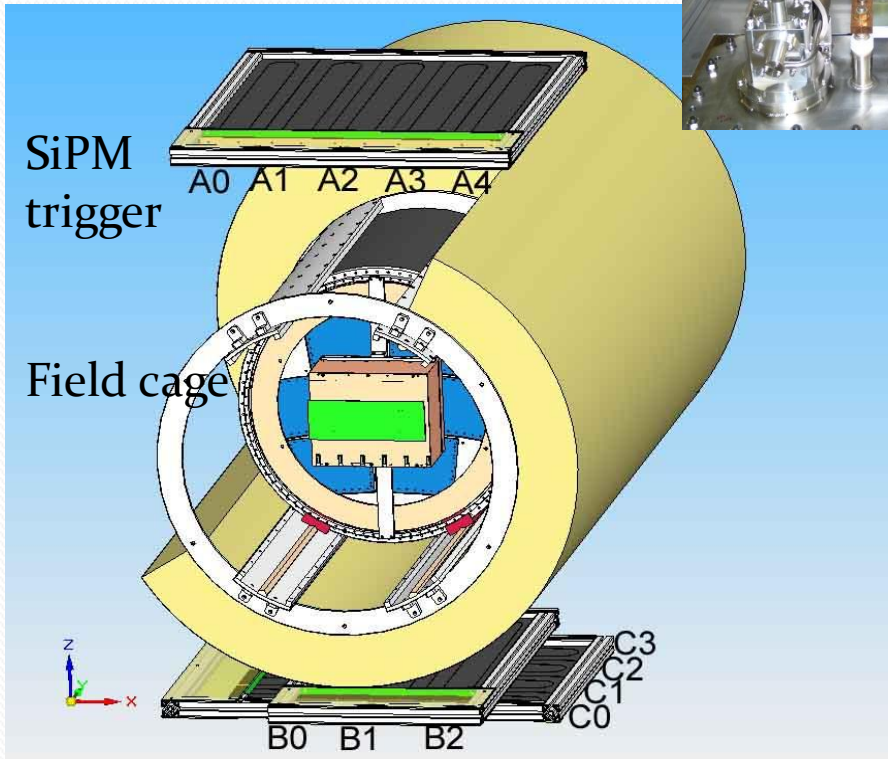
38(*) member
+ 7 observer
institutes
from 12
countries

(*) 25 signed
the MOA

www.lctpc.org

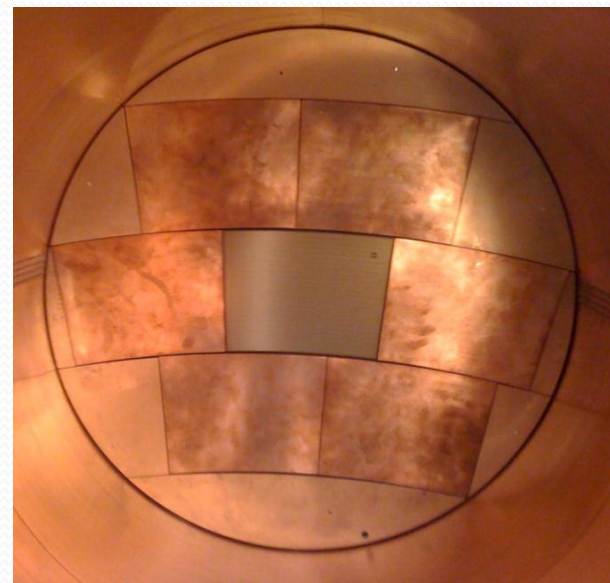
The EUDET test setup at DESY

- The EUDET (FP6) setup at DESY is operational since 2008
- Just upgraded within AIDA (FP7): autonomous magnet with 2 cryo-coolers



Beam tests at DESY : 5 technologies

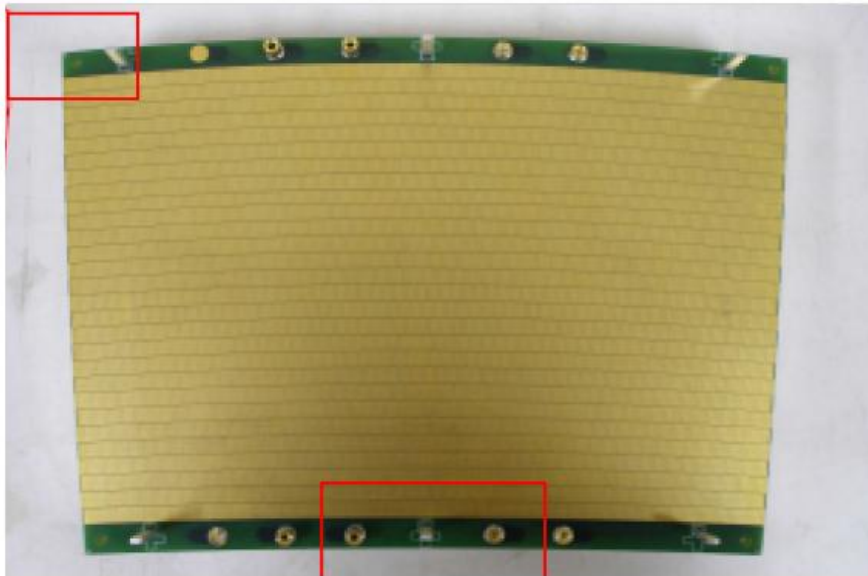
- Laser-etched Double GEMs 100 μ thick ('Asian GEMs')
- Micromegas with charge dispersion by resistive anode
- GEM + pixel readout
- InGrid (integrated Micromegas grid with pixel readout)
- Wet-etched triple GEMs ('European GEMs')



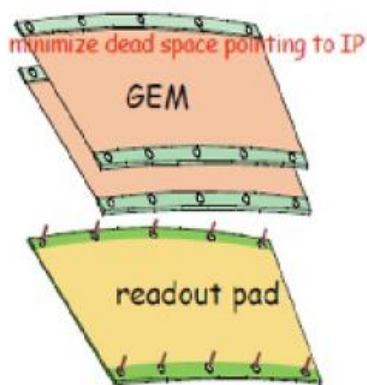
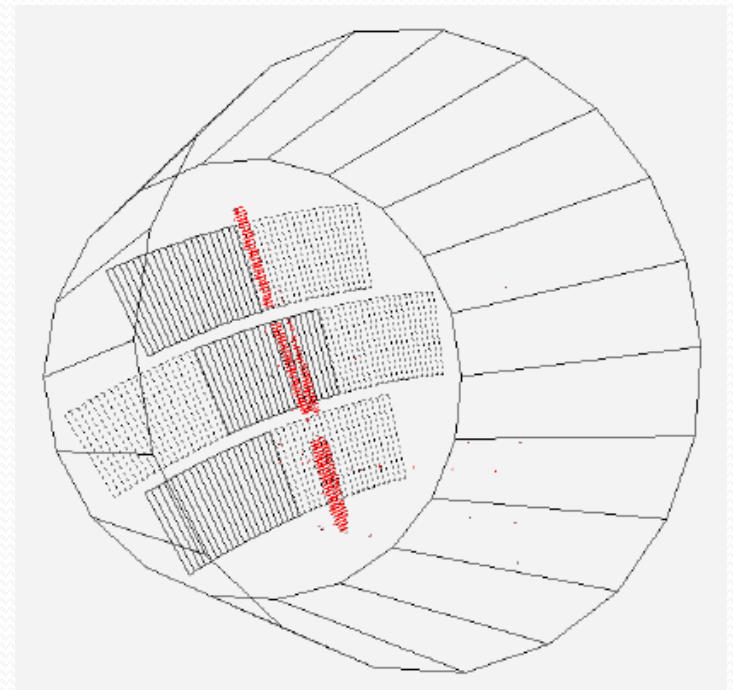
Advantages of MPGDs over wires

- Reduction of ExB effect (improves spatial resolution)
- Less mechanical tension
- Less ageing than wires
- Fast signal $O(\text{few ten ns})$, fast and efficient ion collection
- Natural or tunable suppression of ion backflow
- Discharge probability and consequences can be mastered (use of resistive coatings, several step amplification, segmentation)

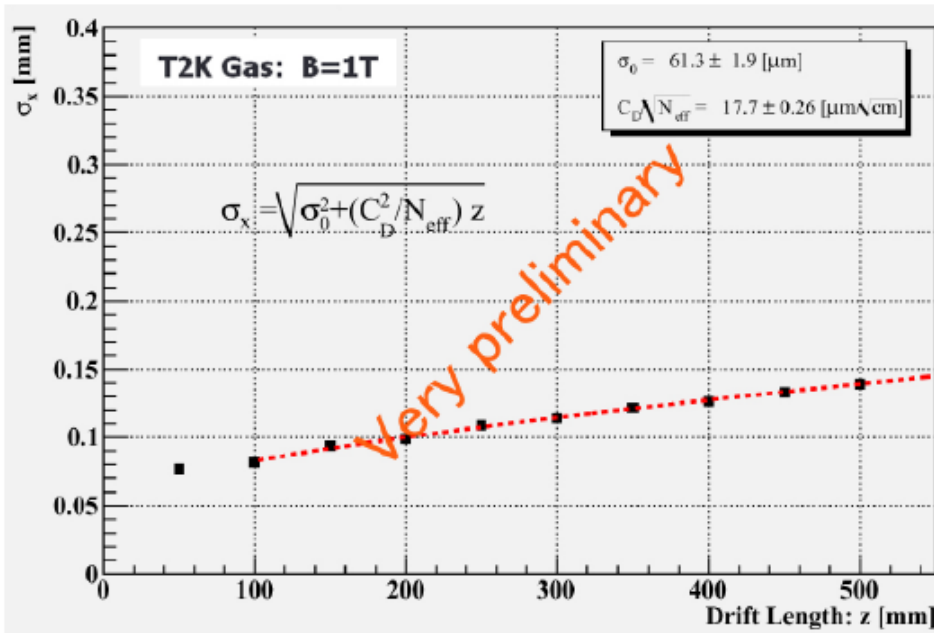
Double GEM Modules (Asian GEMs)



Laser-etched Liquid Crystal Polymer
100 μm thick, by SciEnergy, Japan
28 staggered rows of 176-192 pads
1.2 x 5.4 mm^2

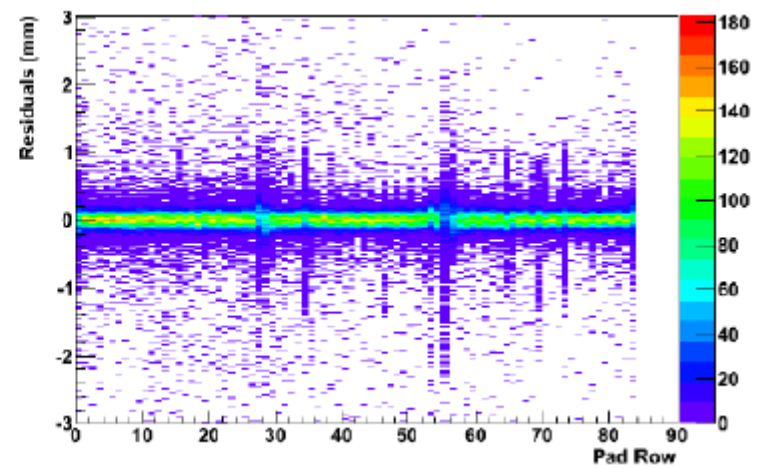
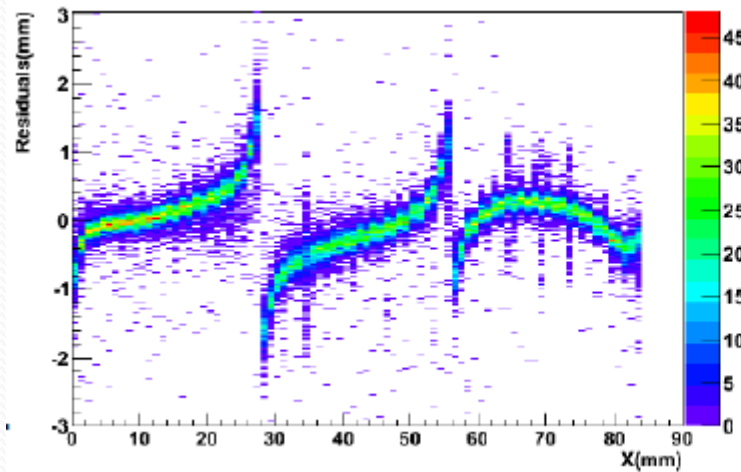


Performance of Double GEMs



$r\phi$ resolution at zero drift: 60 microns
 Behavior consistent with expectation
 from diffusion.

Distortions
 due to HV
 setting on the
 frame :
 corrected
 offline

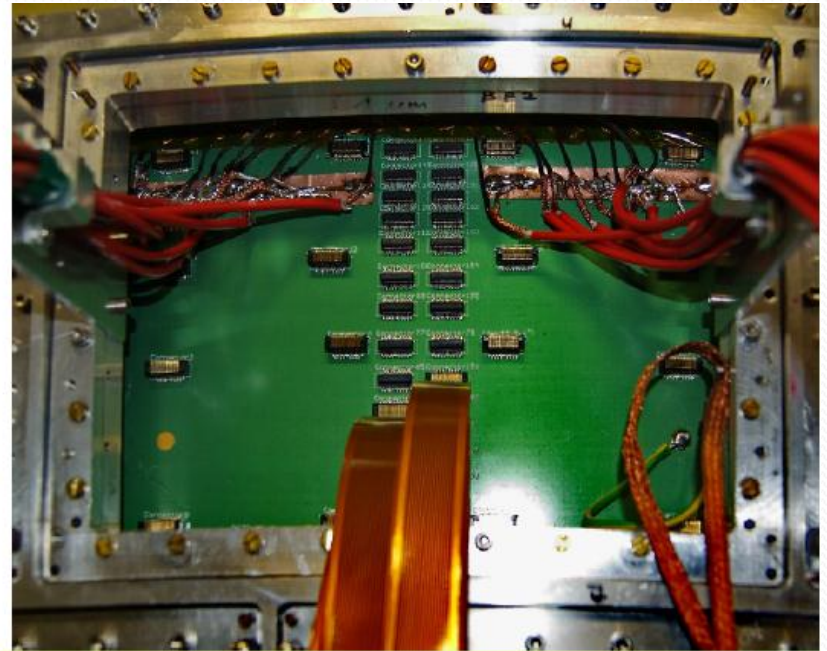
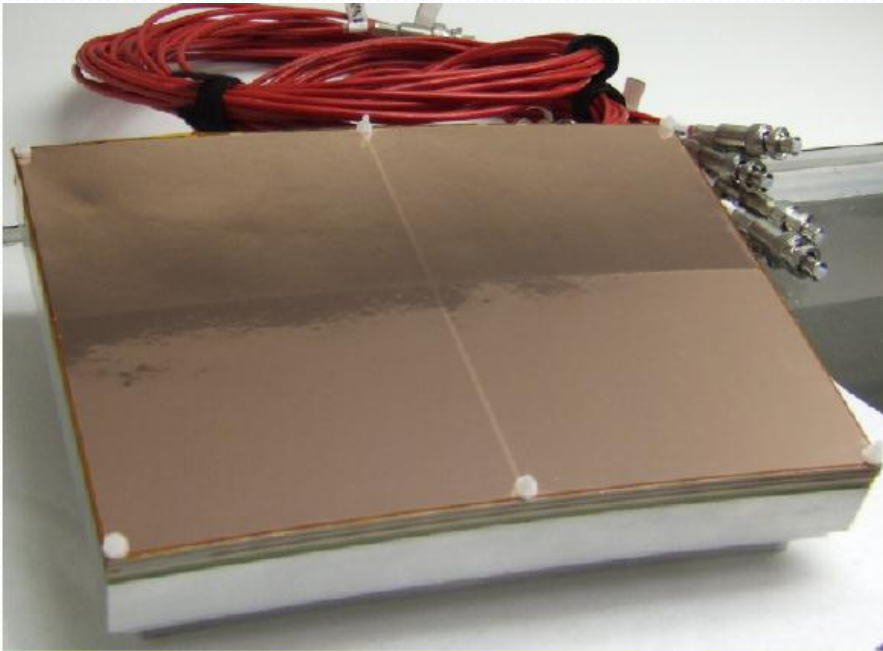


Tripple GEM Module ('European GEMs')

3 standard CERN GEMs mounted on a light ceramic frame (1 mm) and segmented in 4 to reduce stored energy.

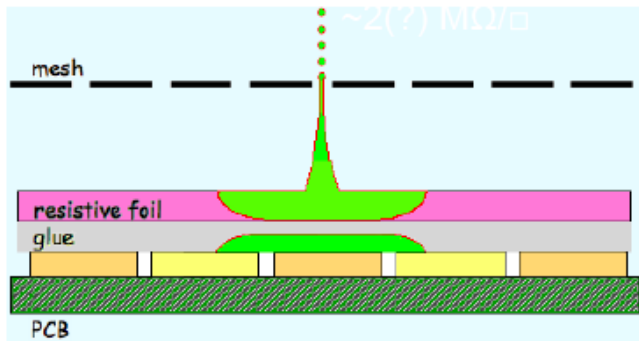
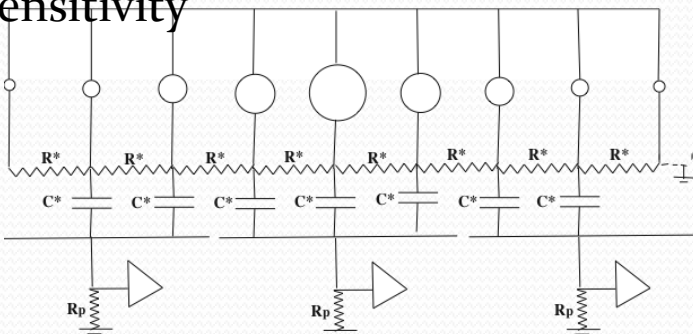
Partially equipped (1000 pads, $1.26 \times 5.85 \text{ mm}^2$)

5000 pad version being built



Charge spreading by resistive foil

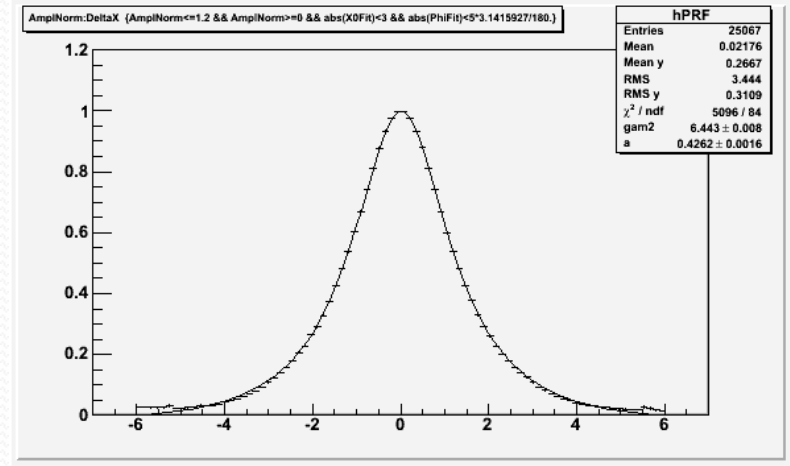
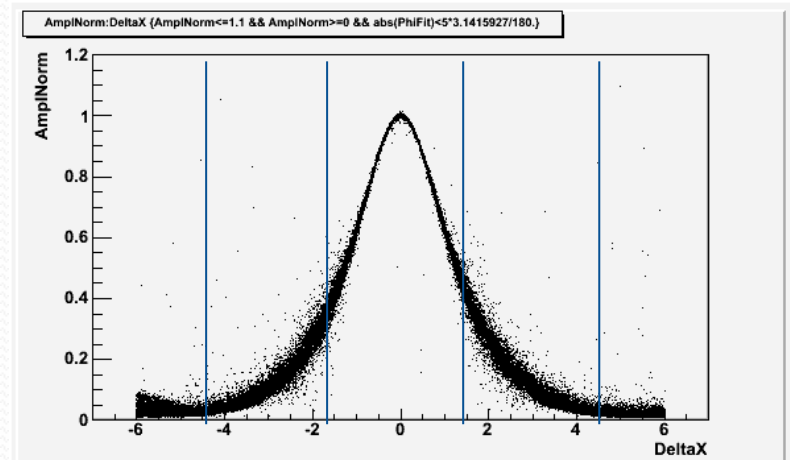
Resistive coating on top of an insulator:
 Continuous RC network which spreads the charge from σ (avalanche) $\sim 15\mu$ to mm: matching pad width improves position sensitivity



M. Dixit, A. Rankin, NIM A 566 (2006) 28

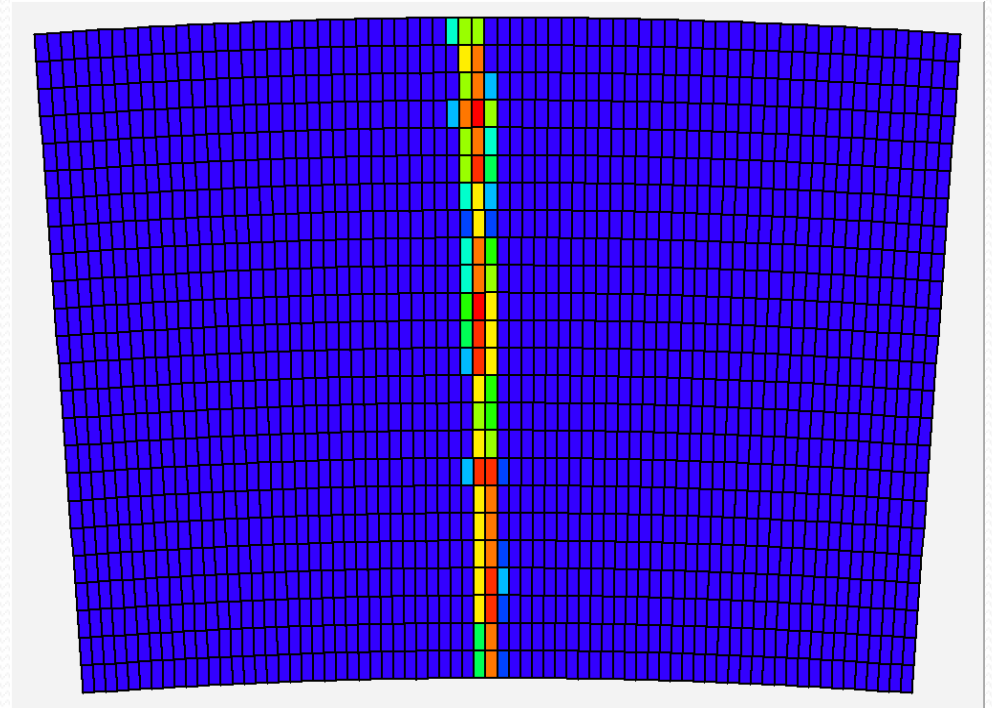
PAD RESPONSE: Relative fraction of 'charge' seen by the pad, vs $x(\text{pad}) - x(\text{track})$

$Z=20\text{cm}$, 200 ns shaping



$x(\text{pad}) - x(\text{track})$ (mm)

Micromegas Modules with resistive coating



24 rows x 72 columns of $3 \times 6.8 \text{ mm}^2$ pads

Various resistive coatings have been tried: Carbon-loaded Kapton (CLK), 3 and 5 Mohm/square, resistive ink.

Uniformity (B=1T data)

MEAN RESIDUAL vs ROW number

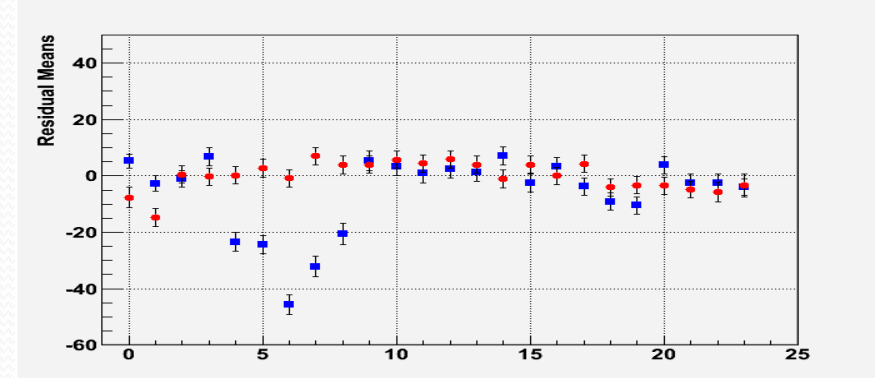
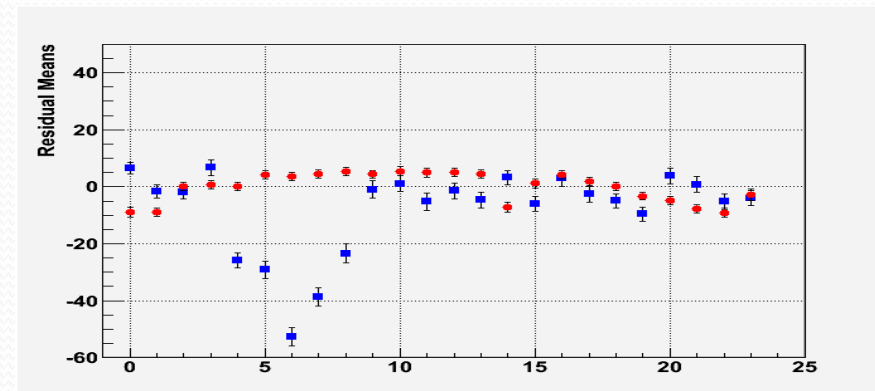
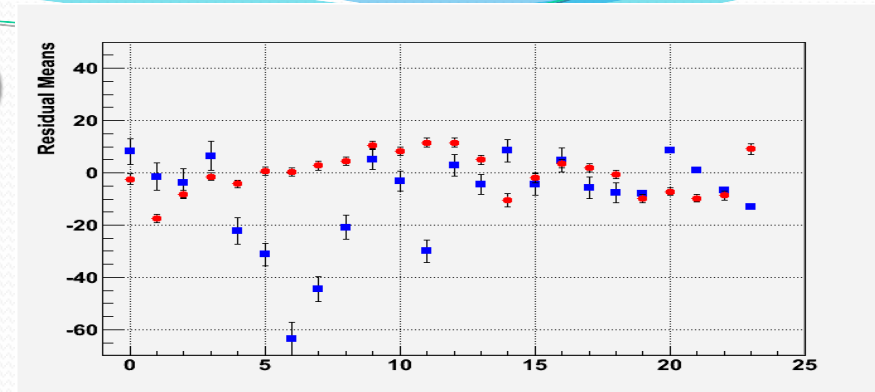
Z=5cm

Z-independent distortions

Distortions up to 50 microns for resistive ink (blue points) Z=35cm

Rms 7 microns for CLK film (red points)

-> select CLK Z=50cm



Row number

Micromegas results (B = 0T & 1T)

Carbon-loaded kapton resistive foil

Gas: Ar/CF₄/Iso 95/3/2

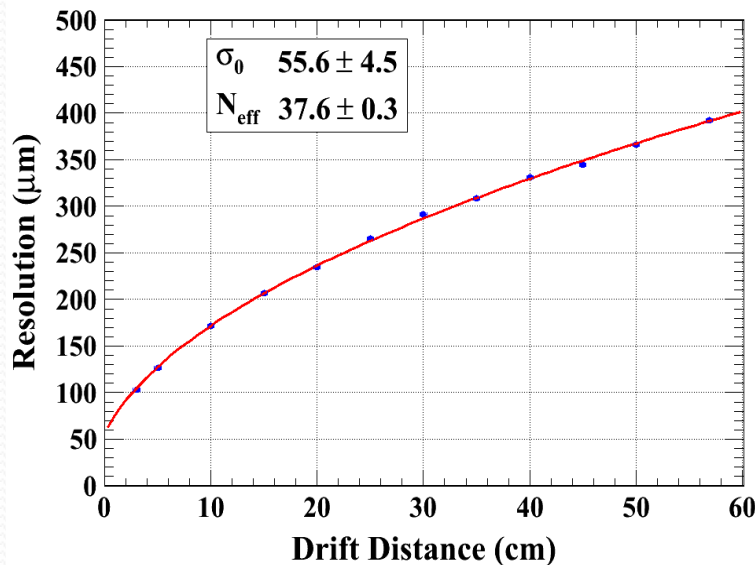
$$\sigma = \sqrt{\sigma_0^2 + \frac{C_d^2 \cdot z}{N_{eff}}}$$

σ_0 : the resolution at Z=0

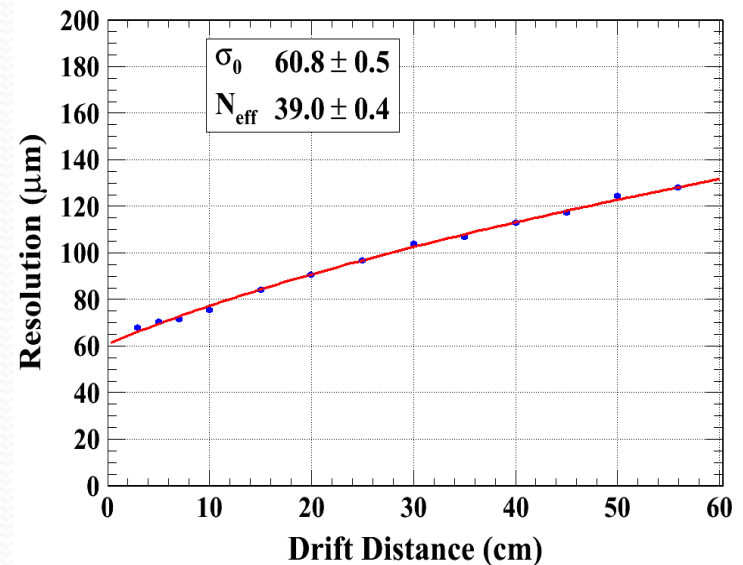
N_{eff} : the effective number of electrons

C_d : diffusion constant

B=0 T $C_d = 315.1 \mu\text{m}/\sqrt{\text{cm}}$ (Magboltz)



B=1 T $C_d = 94.2 \mu\text{m}/\sqrt{\text{cm}}$ (Magboltz)



Module 4 $\left[\begin{array}{l} \chi^2 : 10.6 \\ \text{Ndf: } 10 \end{array} \right]$

Module 3 $\left[\begin{array}{l} \chi^2 : 29.1 \\ \text{Ndf: } 11 \end{array} \right]$

Micromegas results (B = 0T & 1T)

Carbon-loaded kapton resistive foil

Gas: Ar/CF₄/Iso 95/3/2

$$\sigma = \sqrt{\sigma_0^2 + \frac{C_d^2 \cdot z}{N_{eff}}}$$

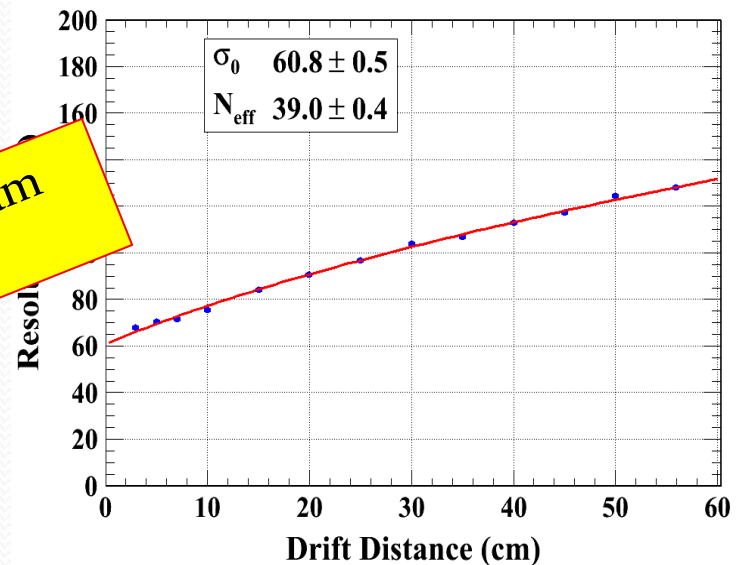
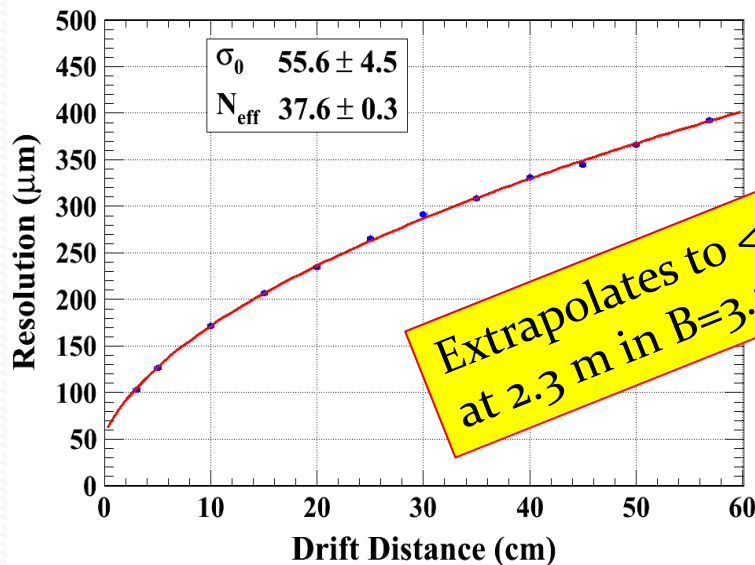
σ_0 : the resolution at Z=0

N_{eff} : the effective number of electrons

C_d : diffusion constant

B=0 T $C_d = 315.1 \mu\text{m}/\sqrt{\text{cm}}$ (Magboltz)

B=1 T $C_d = 94.2 \mu\text{m}/\sqrt{\text{cm}}$ (Magboltz)

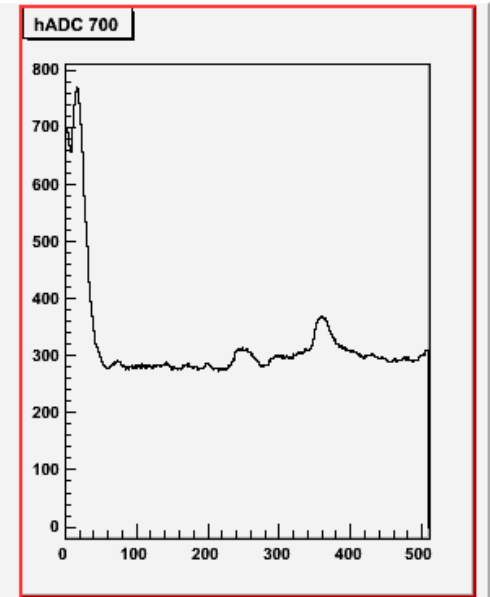
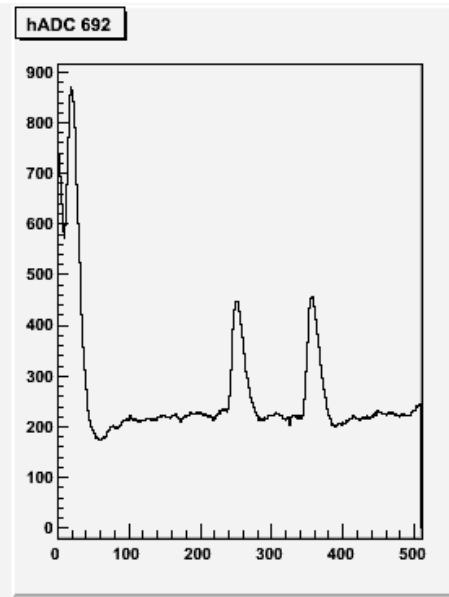
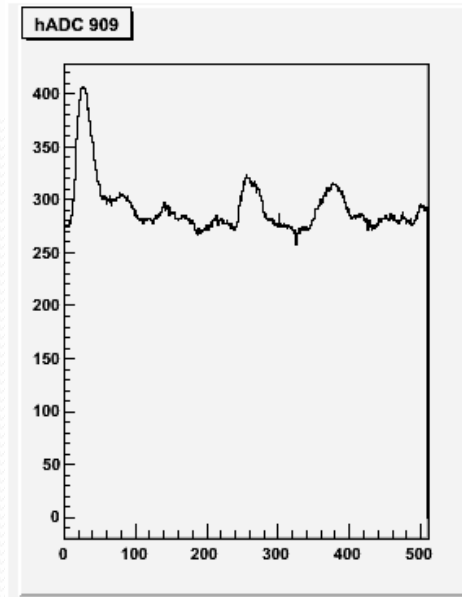
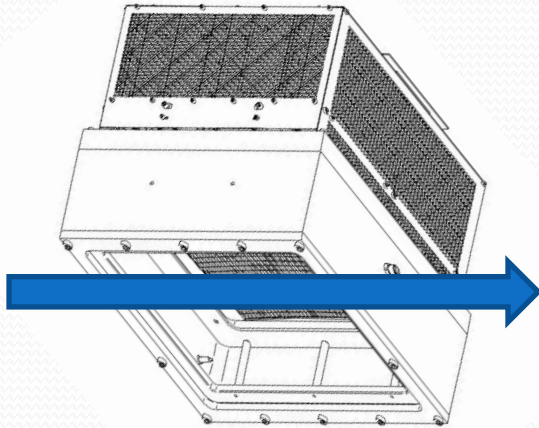


Module 4 $\left[\begin{array}{l} \chi^2 : 10.6 \\ \text{Ndf: } 10 \end{array} \right]$

Module 3 $\left[\begin{array}{l} \chi^2 : 29.1 \\ \text{Ndf: } 11 \end{array} \right]$

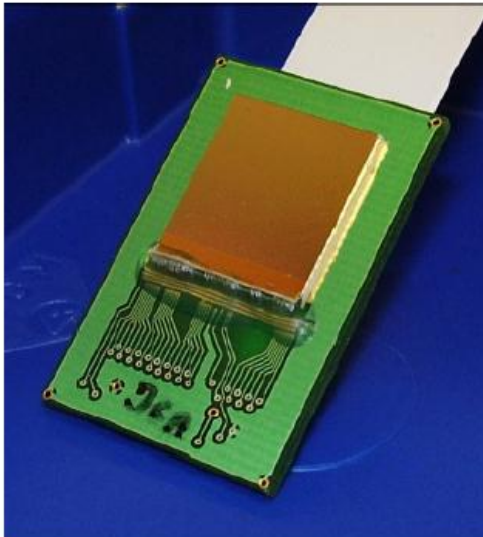
Test in a high intensity π beam

Test at CERN (July 2010) at 180 kHz (5 x 2 cm² beam) showed no charging up and stable operation

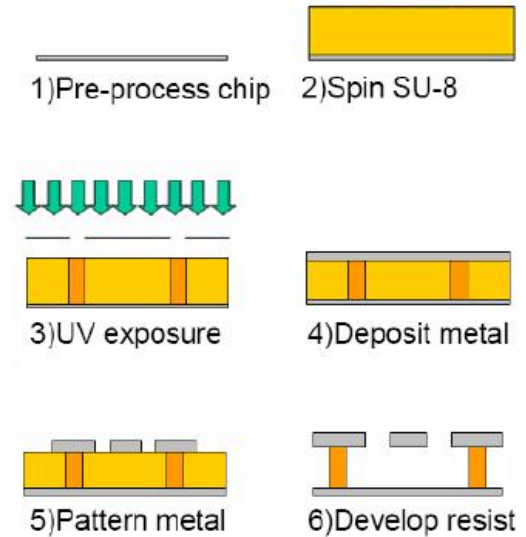


Highly Pixelized Readout

Bump bond pads for Si-pixel detectors serve as charge collection pads.



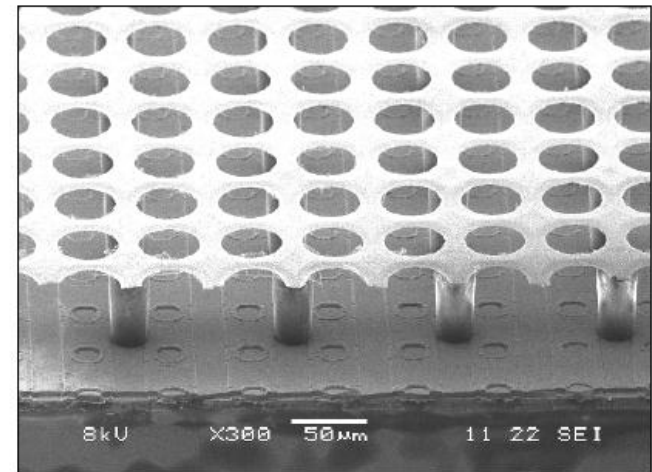
See T. Krautscheid's talk, this session



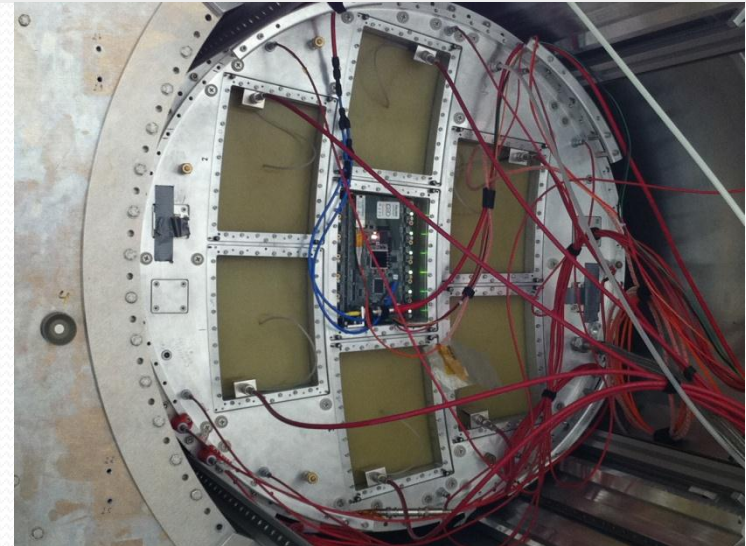
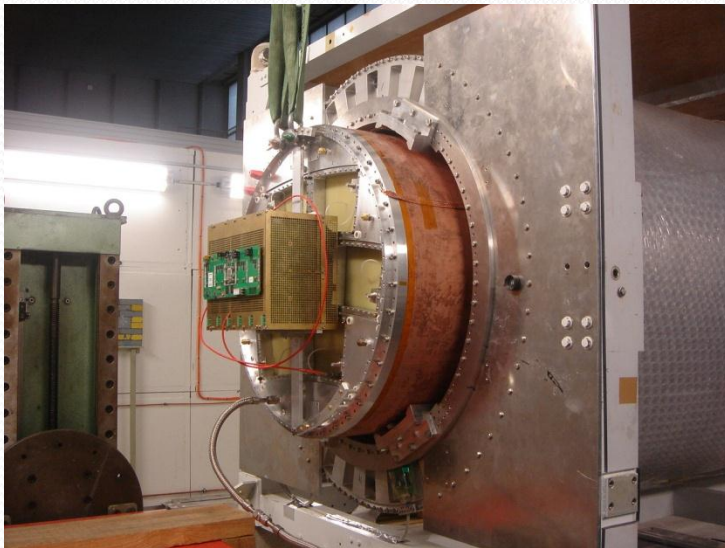
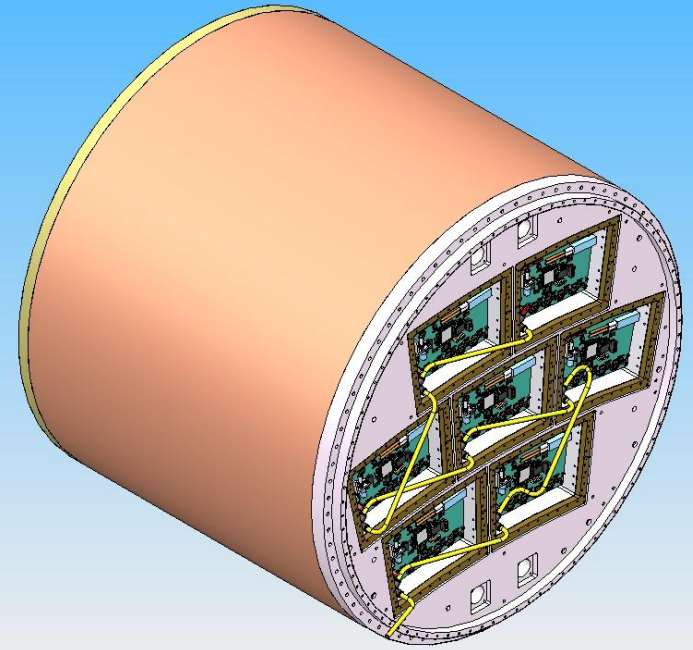
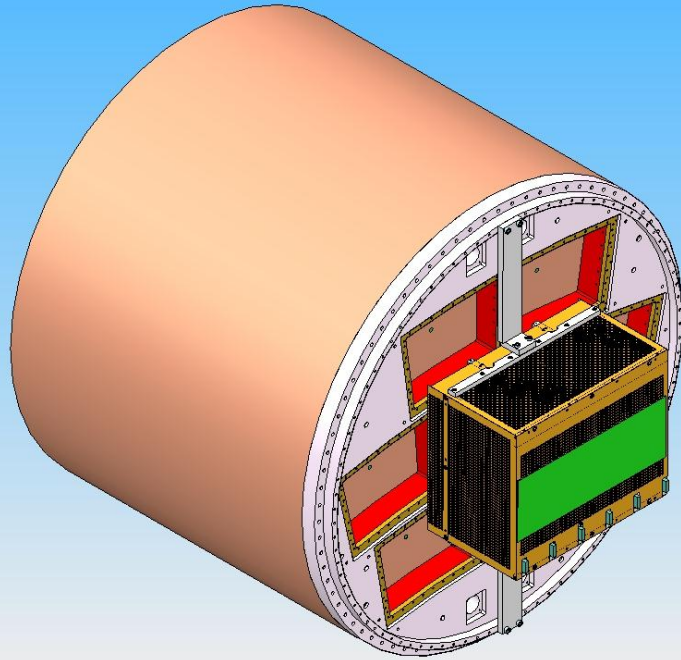
Timepix derived from Medipix-2
 256 × 256 pixels of size 55 × 55 μm²

Each pixel can be set to:

- **TOT** ≈ integrated charge
- **Time** between hit and shutter end



7 module project – Micromegas electronic integration



Integration of the T2K electronics

- New detector : new routing to adapt to new connectors, lower anode resistivity ($3 \text{ M}\Omega/\text{sq}$), new res. foil grounding on the edge of the PCB.
- New 300 points flat connectors (zero extraction force)
- New front end: keep naked AFTER chips and remove double diodes (count on resistive foil to protect against sparks)
- New Front End Mezzanine (FEMI)
- New back-end for up to 12 modules
- New DAQ, 7-module ready and more compact format
- New trigger discriminator and logic (FPGA).

Integrated electronics for 7-module project

FEC

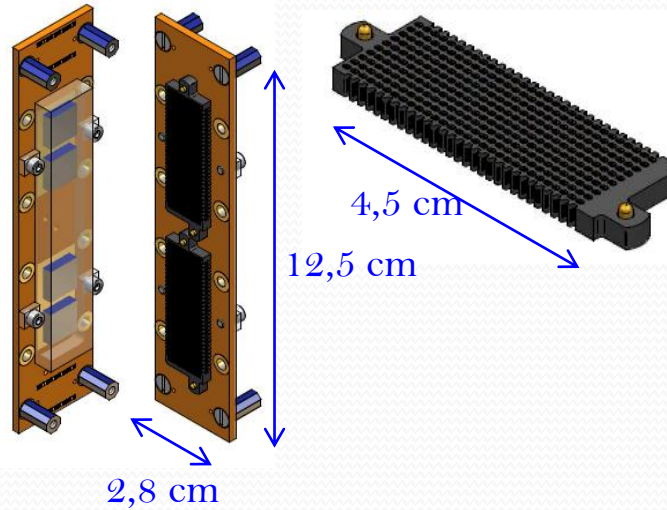
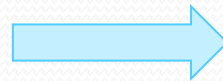


25 cm

14 cm

3,5 cm

- Remove packaging and protection diodes
- Wire-bond AFTER chips
- Use 2 × 300 pins connector



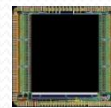
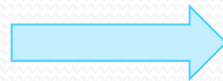
Chip



3,5 cm

0,78 cm

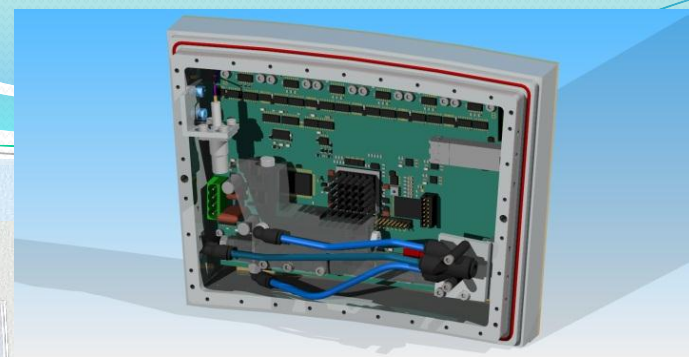
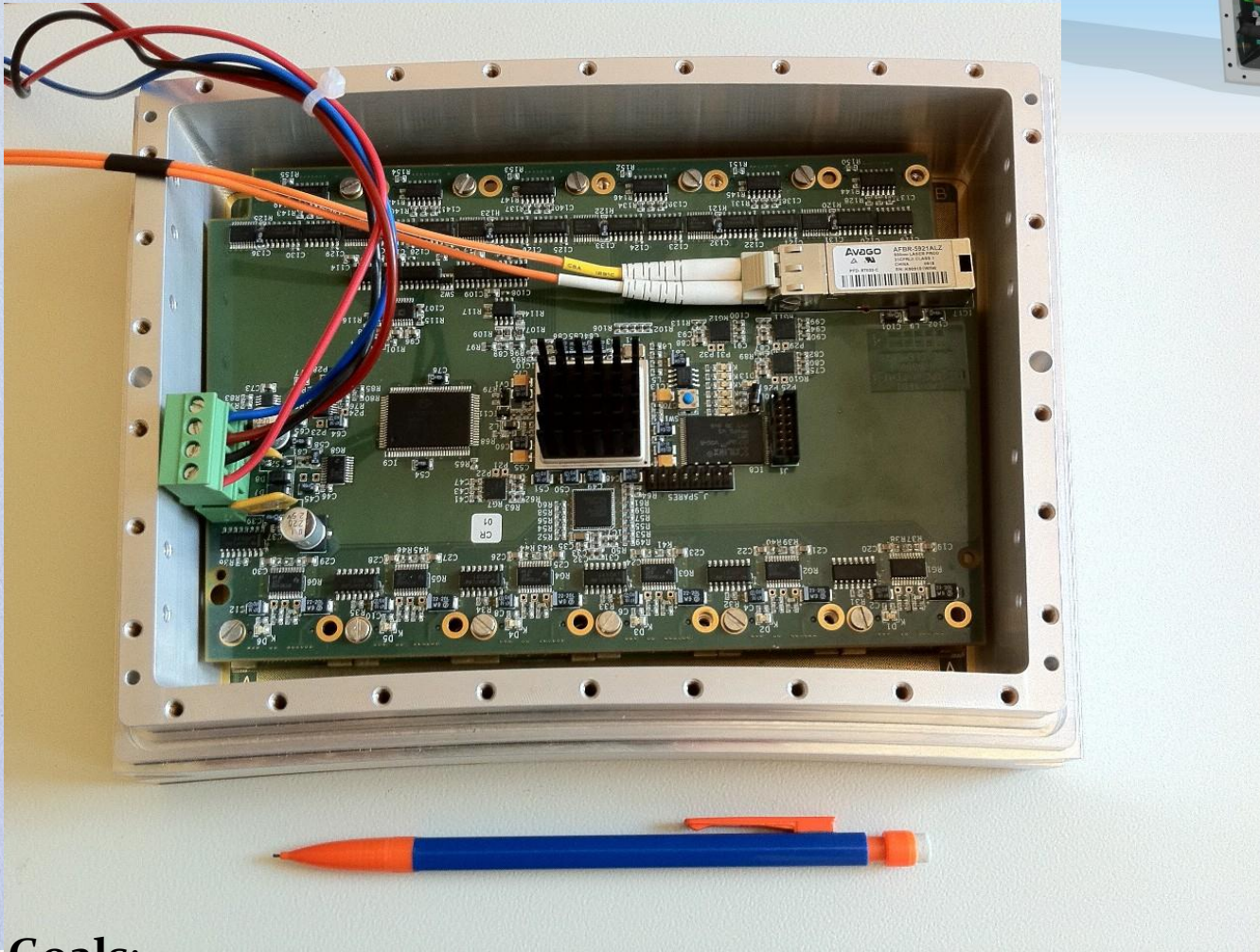
0,74 cm



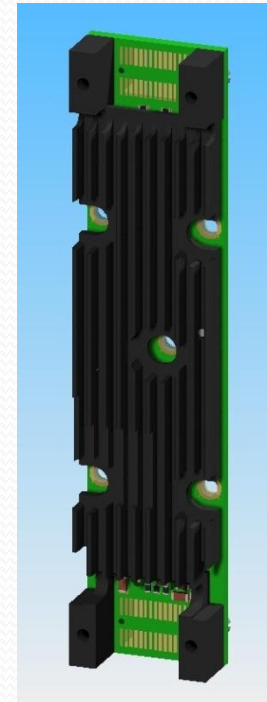
after 2 weeks of operation: no ASIC lost:

The resistive foil protects against sparks

The goal of $< 25\%$ Xo is attained

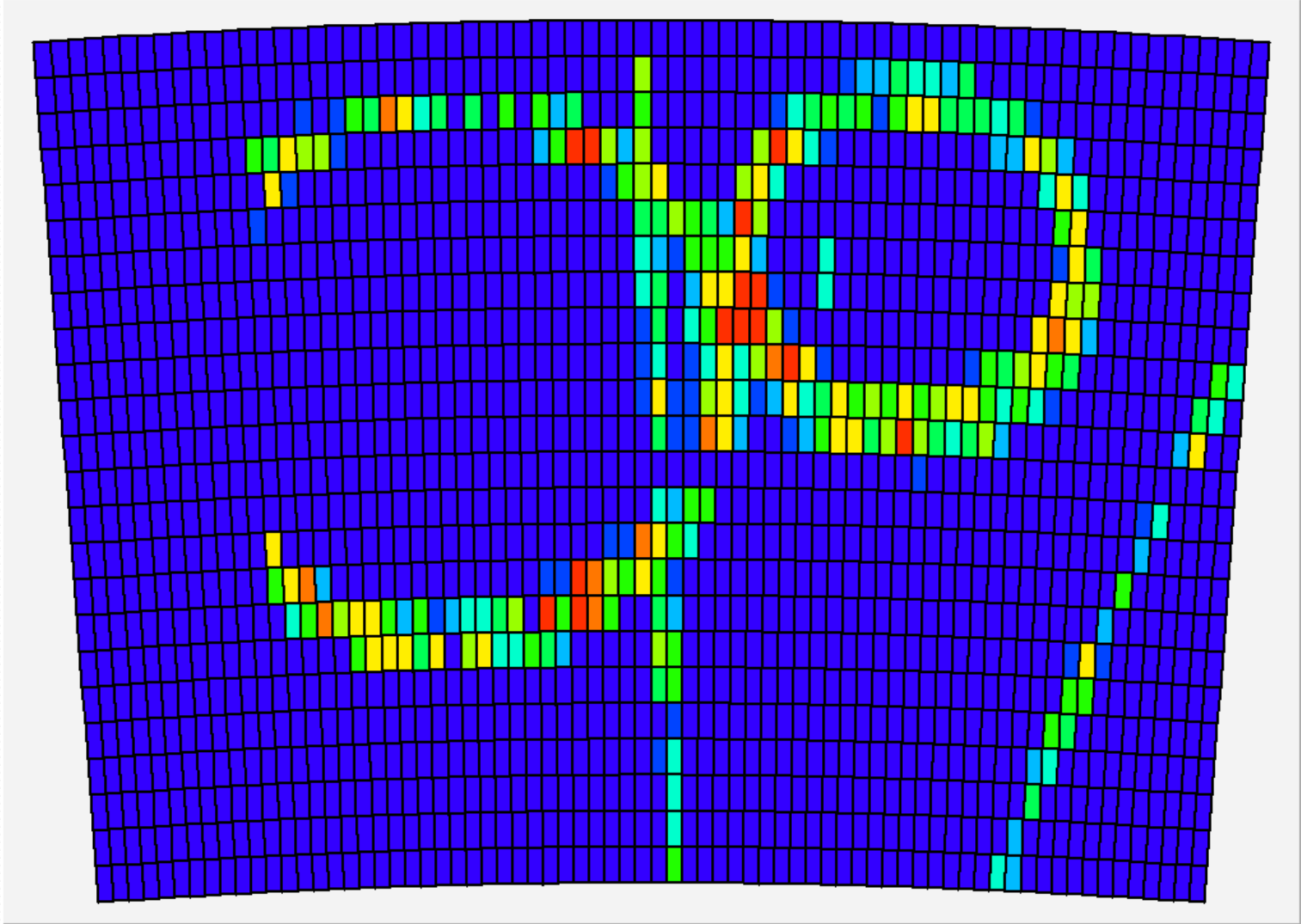


radiator

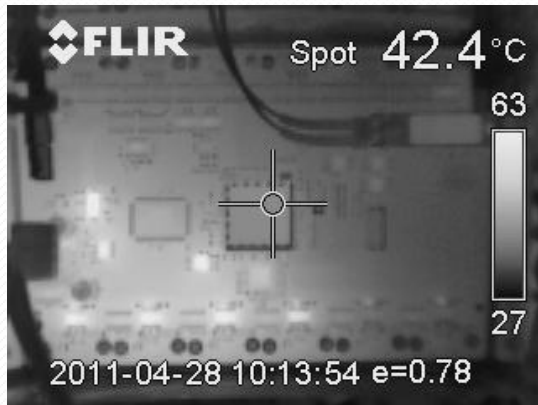


Goals:

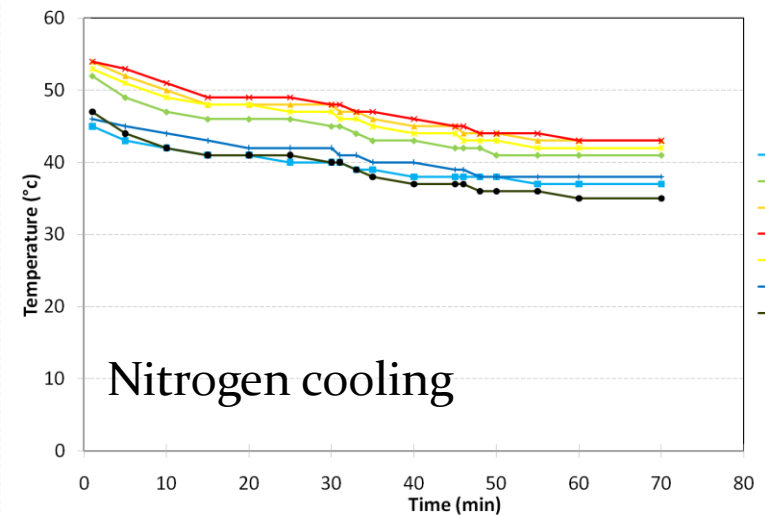
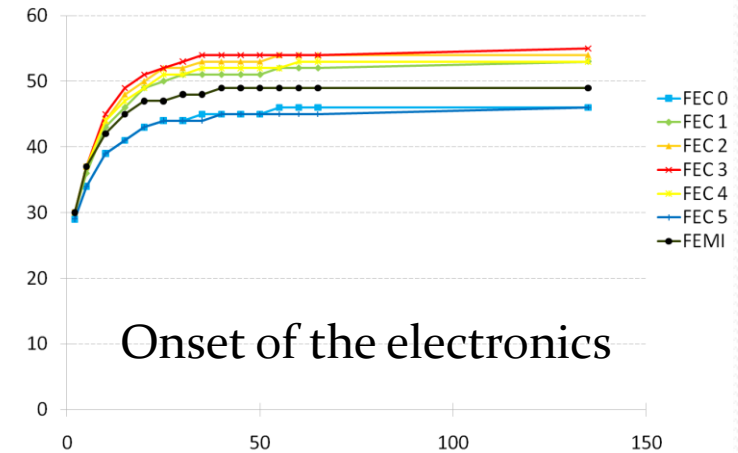
- test of full integration
- test of quasi industrial production, with characterization and quality procedures



- **Thermal studies.** IR camera shows hot spots (regulators, ADC). T-probes on every component.

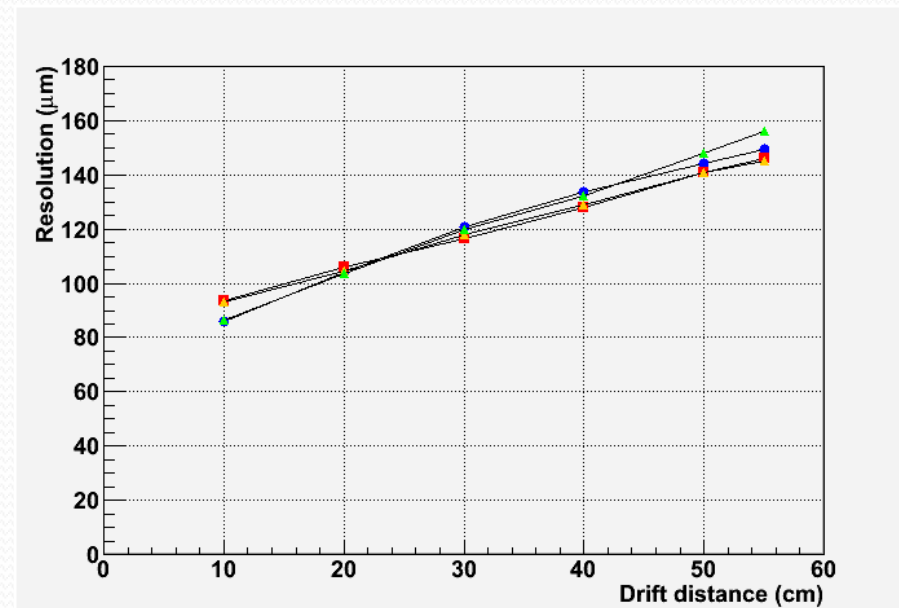
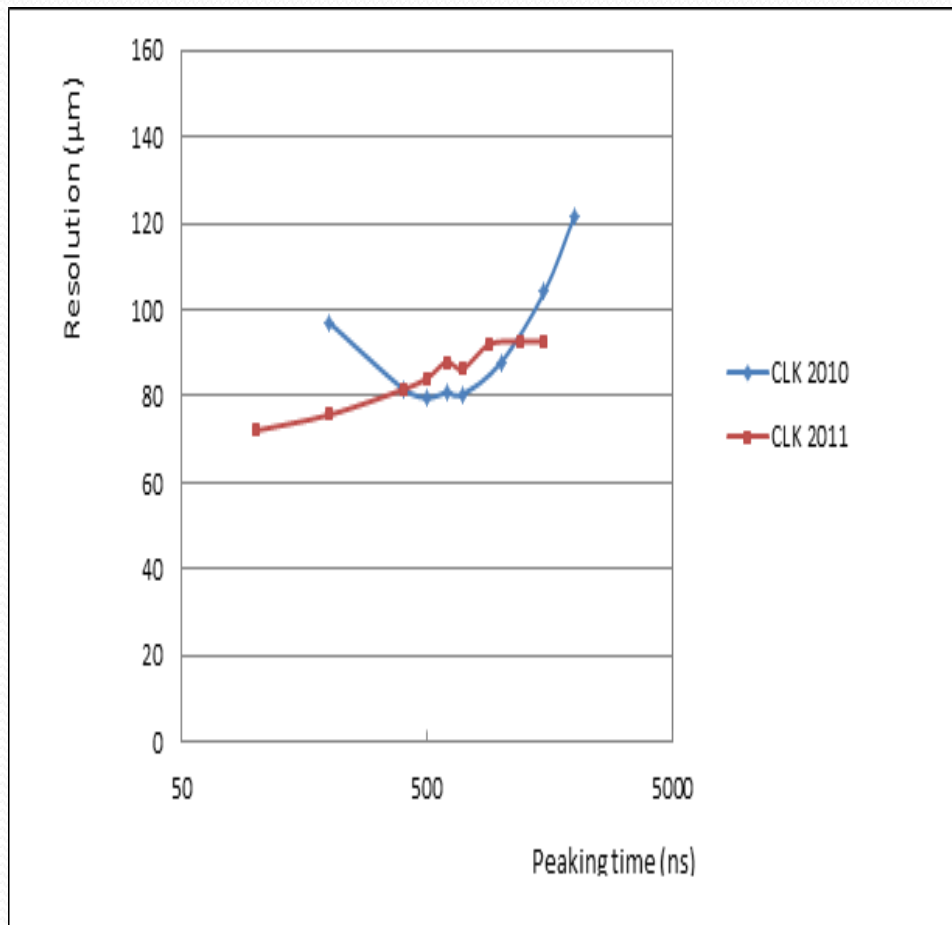


2-phase CO₂ cooling under study (KEK, Nikhef)



Preliminary results (May 2011) : resolution (B=1T data)

- Confirms previous measurements (excl. rows with ASICs in bad contact).
- Optimum resolution now obtained for peaking time below 200 ns : good for 2-track separation



Resolution vs z for various peaking times.

New End Plate

Material budget requirement for final end plate: $8\% X_0$

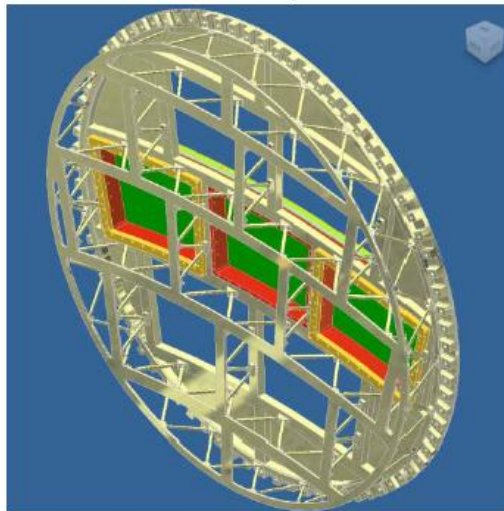
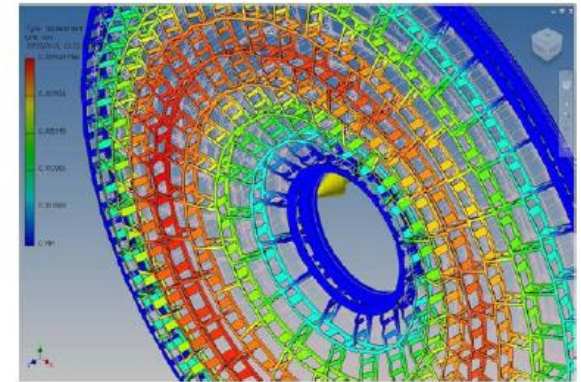
→ Finite Element Analysis of final end plate

Deflection of $220\ \mu\text{m}$ for overpressure of 2.1 mbar

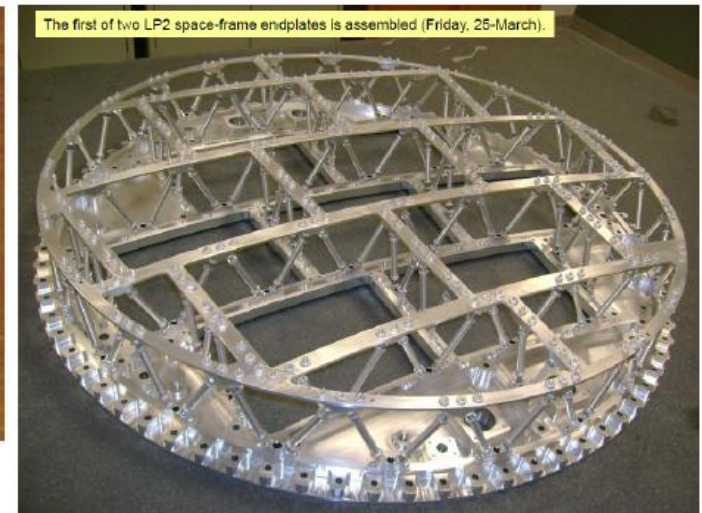
Several materials and designs have been studied
Strut space-frame design provides greatest strength-to-material.

Second end plate for LP designed and built (8.8 kg)

Preliminary measurements of deflection are very close to requirements



strut space-frame
test structure



The first of two LP2 space-frame endplates is assembled (Friday, 25-March).

Ion disk and gating

- During 1 ms every 200 ms, bunch crossings produce ionization in the gas: positive ions drift very slowly to the cathode. Ions produced in the avalanches near the anode drift all the way back to the cathode, resulting in a slowly moving ion sheet.
- Background evts have been simulated and charge density and resulting electric field estimated. Preliminary results :

Primary ionization gives up to $8.5 \mu\text{m}$ distortions (can be tolerated)

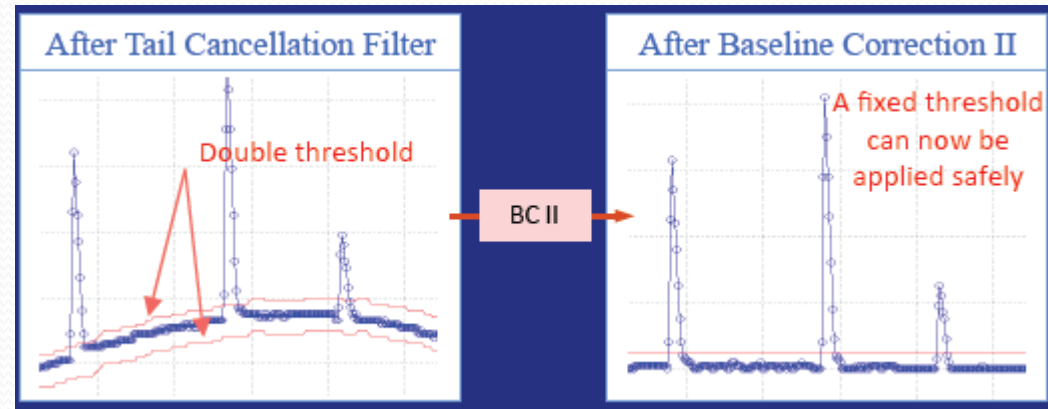
‘ion sheet’ effect results in 60μ distortions (not acceptable)

With a gating grid near the anode, this can be reduced to a negligible amount.

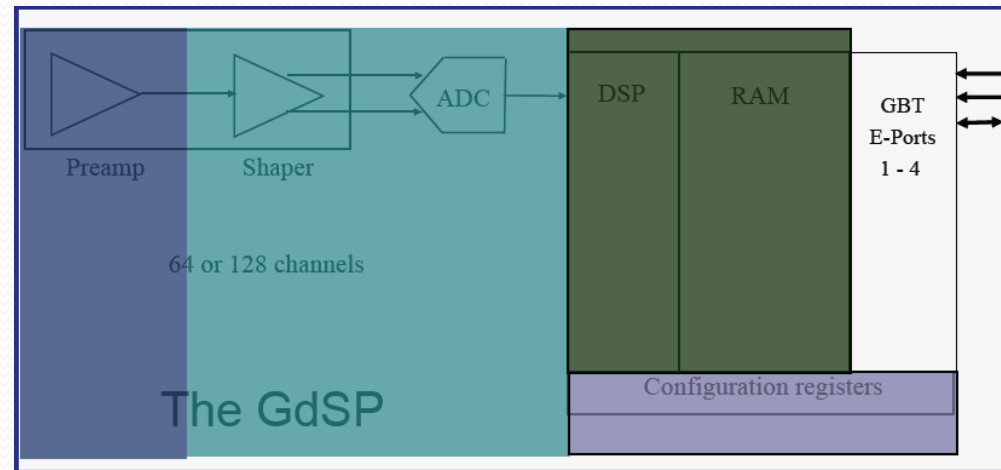
- -> gating is necessary between train crossings

Preparation for future electronics

- Design and optimization work in progress for a new chip GdSP, evolution from SALTRO₁₆:
 - 64 or 128 channels
 - 130 nm technology
 - Very low noise
 - Integrated ADC
 - Low power consumption (all-inclusive 7-8 mW/ch)
 - 6 different power regions for power cycling
 - High level filtering (baseline subtraction, spike removal)

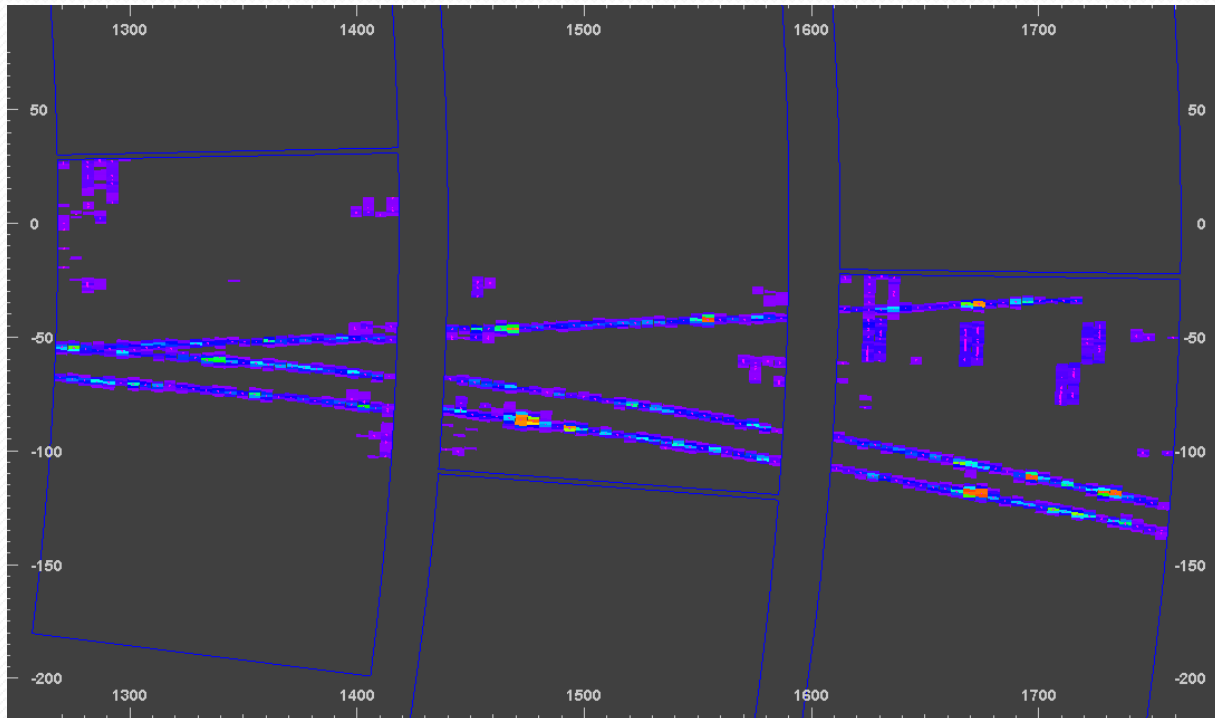


Gaseous detector Signal Processor, P. Aspell *et al.*



Software : track reconstruction and fitting

- Going from various programs for track reconstruction to one (Marlin TPC) within LC framework
 - Can serve for all beam test prototypes and for ILD simulation data
 - Allow multi-module alignment
 - Kalman filter track finding and fitting

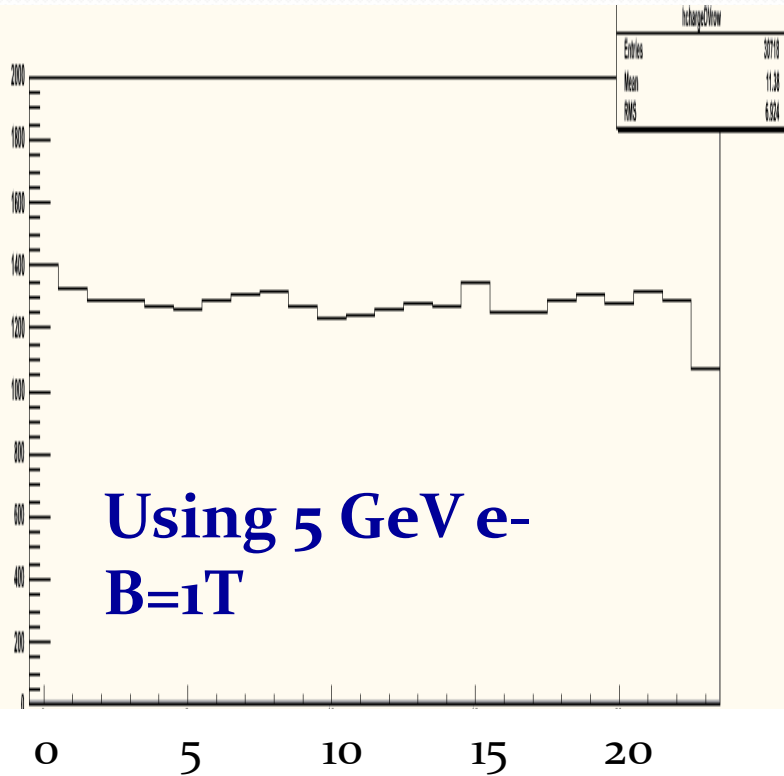


CONCLUSIONS

- MPGDs have been shown to fulfill the requirements for the readout of a TPC for the LC.
- Pixel readout needs more development to gain in reliability and operability in large surfaces.
- Integration work (electronics and cooling) is going on, and practical production issues are addressed for the pad readout.
- All aspects/limitations are being addressed to be included in the 'Detector Baseline Document'

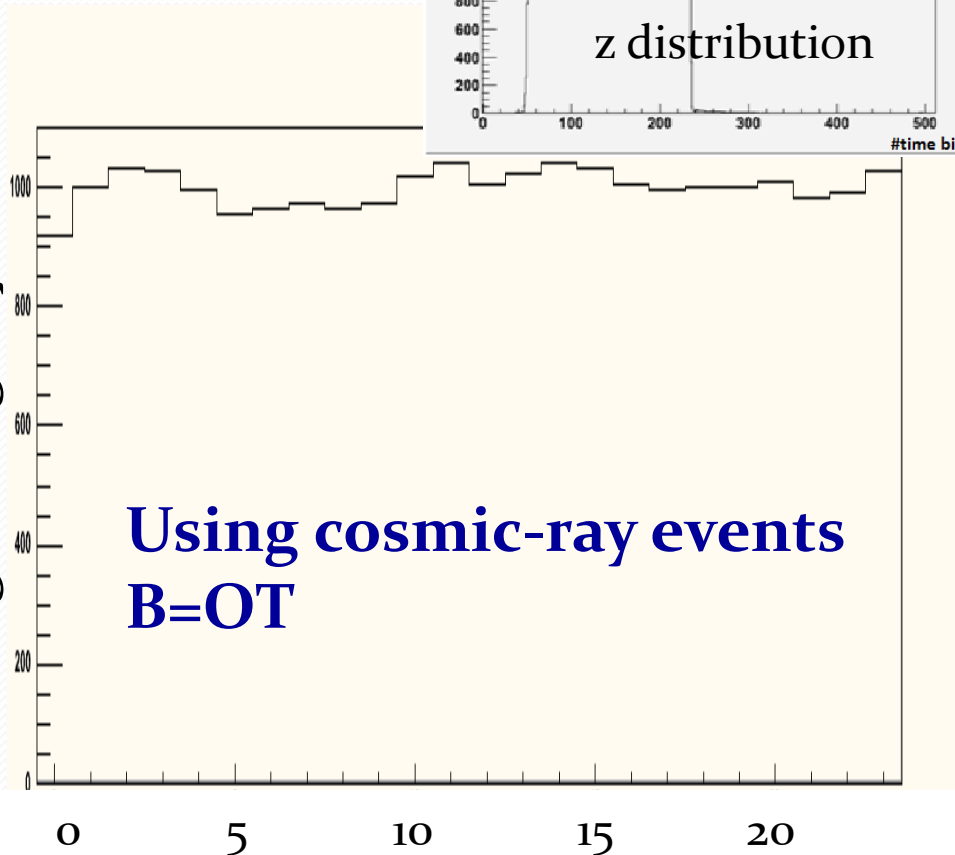
Uniformity

Average charge by row



Using 5 GeV e-
B=1T

Average charge by row



Using cosmic-ray events
B=0T

Excellent uniformity up to the edge of the module,
thanks to the 'bulk' technology.

N_{eff} measurement with Micromegas

Averaging $B=0\text{T}$ and $B=1\text{T}$ data, modules 4, 5 and 3 (excluding ink module):

- $N_{\text{eff}} = 38.0 \pm 0.2(\text{stat})$ (systematics difficult to assess)
- $\sigma_o = 59 \pm 3 \mu\text{m}$

$$N_{\text{eff}} = \frac{1}{\langle 1/N \rangle} \frac{\langle G \rangle^2}{\langle G^2 \rangle}$$

D. Arogancia et al.,
NIM A 602 (2009) 403

Note that $1/\langle 1/N \rangle = 47.1$ from Heed for 5 GeV electrons on 6.84mm long pads.

Thus N_{eff} has to be between 23.5 (for exponential gain fluctuations) and 47.1 if there are no gain fluctuations.

$1/\langle 1/N \rangle = 34.9$ for 5.4 mm pads (GEM case).